

08-28-00

CPA/GAU 1763

OIP

CONTINUED PROSECUTION APPLICATION

Customer No. 20350
TOWNSEND and TOWNSEND and CREW LLP

AUG 25 2000



Atty. Docket No. AM-1126/T08910 (016301-08910US)

"Express Mail" Label No. EL 381 322 390 US
Date of Deposit August 25, 2000

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By Ron Anton
Ron Anton

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Sir:

This is a request under 37 CFR 1.53(d) for filing a CPA

☒ Continuation ☐ Division

of application No. 09/362,504, filed July 27, 1999.

of (list each inventor) Kramadhiti V. Ravi, Kent Rossman, Turgut Sahin and Pravin Narwankar

for METHOD FOR REDUCING THE INTRINSIC STRESS OF HIGH DENSITY PLASMA FILMS

Applicant understand that this CPA application automatically ABANDONS the parent application.

☒ Please enter the enclosed preliminary amendment.

Claims after Entry of any Amendments, Less any Cancelled Claims

(Col. 1)

(Col. 2)

FOR:	NO. FILED	NO. EXTRA
BASIC FEE		
TOTAL CLAIMS	21-20=	1
INDEP CLAIMS	5-3=	2
<input type="checkbox"/> MULTIPLE DEPENDENT CLAIM PRESENTED		

SMALL ENTITY

RATE	FEE
	\$345
x9=	\$
x39=	\$
+130=	\$
TOTAL	\$

OR

NOT SMALL ENTITY

RATE	FEE
	\$690
x18=	\$18
x78=	\$156
+260=	\$
TOTAL	\$864

* If the difference in Col. 1 is less than zero, enter "0" in Col. 2

Please charge Deposit Account No. 20-1430 as follows:

☒ Filing fee

☒ Any additional fees associated with this paper or during the pendency of this application

☐ The issue fee set in 37 CFR 1.18 at or before mailing of the Notice of Allowance, pursuant to 37 CFR 1.311(b).

\$ 864

#11
8/30/00
MW

Respectfully submitted,

TOWNSEND and TOWNSEND and CREW LLP

Please send all correspondence to:
PATENT COUNSEL
APPLIED MATERIALS, INC.
P.O. BOX 450A
SANTA CLARA, CA 95052

Chun-Pok Leung
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Reg. No.: 41,405
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PA 154390 v1
PA 3092418 v1

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08 7/24/00 650.00 CH
08 7/24/00 10.00 CH
08 7/24/00 155.00 CH

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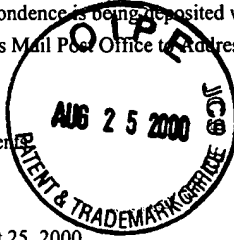
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TOWNSEND and TOWNSEND and CREW LLP

By: Ron Anton



PATENT

Attorney Docket No.: A1126/T08910
TTC No.: 16301-008910

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#121
8/30/00
MW

In re application of:

KRAMADHATI V. RAVI et al.

Application No.: 09/362,504

Filed: July 27, 1999

For: METHOD FOR REDUCING THE
INTRINSIC STRESS OF HIGH
DENSITY PLASMA FILMS

Examiner: Rudy Zervigon

Art Unit: 1763

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced application, please enter the following amendments and remarks.

IN THE CLAIMS:

Please amend claims 16-18, and 32. Note that the remaining claims are unamended, but are reproduced below for the Examiner's convenience and reference.

16. (Thrice amended) An integrated circuit formed on a semiconductor substrate by the method of:

- a) flowing a process gas into a substrate processing chamber;
- b) forming a plasma from said process gas by coupling sputtering energy into said substrate processing chamber;

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